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(71) Applicant *(for all designated States except US)*: **LINTEC CORPORATION** [JP/JP]; 23-23, Honcho, Itabashi-ku, Tokyo 173-0001 (JP).

(72) Inventors; and
(75) Inventors/Applicants *(for US only)*: **SUMI, Takaji** [JP/JP]; 43-7, Yamato-cho, Itabashi-ku, Tokyo 173-0012 (JP). **YAMAZAKI, Osamu** [JP/JP]; 7-7-3, Tsuji, Saitama-shi, Saitama 336-0026 (JP). **SUGINO, Takashi** [JP/JP]; 1-13-18, Saiwaicho, Kawaguchi-shi, Saitama 332-0016 (JP). **SENOO, Hideo** [JP/JP]; 3-33-2, Totsuka, Kawaguchi-shi, Saitama 333-0811 (JP).

(74) Agent: **SUZUKI, Shunichiro**; SUZUKI & ASSOCIATES, Gotanda Yamazaki Bldg. 6F, 13-6, Nishigotanda 7-chome, Shinagawa-ku, Tokyo 141-0031 (JP).

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(54) Title: ADHESIVE TAPE

(57) Abstract: Disclosed herein is an adhesive tape comprising a base and, superimposed thereon, an adhesive layer, this adhesive layer comprising an adherent component (A), an epoxy resin (B), a thermally active latent epoxy resin curing agent (C), an energy radiation polymerizable compound (D) and a photopolymerization initiator (E), wherein either or both of the epoxy resin (B) and energy radiation polymerizable compound (D) have a dicyclopentadiene skeleton in its molecule or molecules thereof. The provided adhesive tape has an adhesive layer which realizes reduction of the water absorption of an adhesive curing product and which enables lowering the elastic modulus thereof at thermocompression bonding.